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			US-PGPUB;	17:41
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	į		IBM_TDB	2004/10/22
	2	(shoshani-ziv).in.	USPAT;	
	_ }	•	US-PGPUB;	17:42
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1		("6606023").PN.	USPAT;	2004/10/22
	1	( 6600023 ).IN.	US-PGPUB;	17:49
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	ì		USPAT	2004/10/22
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}		"4514620"   "4534889"   "4545926"		17.35
		"4560498"   "4591700"   "4689475"		
		"4724417"   "4774024"   "4800253"		
		"4935156"   "5049850"   "5166658"		
		"5378407"   "5382938"   "5451919"		
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	}	"5831510"   "5852397"   "5864281"		1
		"5907273"   "6020808"   "6172591").PN.		2004/10/22
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,		"3061501"   "3138686"   "3187164"		17:53
		"3243753"   "3351882"   "3571777"		
		"3619560"   "3654533"   "3673121"		
		3013300		
		3009/30		
		3023217   3021320		
		"3861029"   "3878501"   "3914363"		
		"3976600"   "4101862"   "4151126"		·
		"4151401"   "4177376"   "4177446"		
		"4237441"   "4238812"   "4246468"		
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	1	"5250228"   "5280263"   "5303115"		
	1	"5351390"   "5358793"   "5401154"		
		"5699607"   "5777541"   "5802709"		
		"5812048"   "5831510"   "5852397"		
		"5864281").PN.		
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Search History 10/22/04 6:25:46 PM Page 1

Second   Setched or etching) with foil)   Second   Setched or etching   With foil)   Substrate   Second   Second   Substrate   Second					2003/06/04
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etching  with foil)   19/5/.ccls. and (photoresistive and substrate) and (letch or etched or etching) with foil)   11/29/5.ccls. and (resistive ad) (film or layer or coat or coating) and substrate and (letch or etched or etching) with foil)   17/29/5.ccls. and (resistive ad) (film or layer or coat or coating) and substrate and (letch or etched or etching) and substrate and (resistive ad) (film or layer or coat or coating)) and substrate and (letch or etched or etching) and foil)   USPAT   2003/06/04   16:12   USPAT   2003/06/04   16:10   USPAT   2003/06/04   16:12   USPAT   2003/06/04   1	ļ		substrate) and ((etch or etched or		15:56
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1862144   1838019   19N.   1808019	-	8	("44/9890"   4010010   40/0/40		16:30
28			"516Z144"   52601/0   533030/		
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etched or etching) and (foil with (thick or thickness or width))  ((method or process) with resistor) and (resistive adj (film or layer or coat or coating)) and substrate and ((etch or etched or etching or polishing) with  foil)  ("2945180"   "3808576"   "3813631"   USPAT   19:42  "4174513"   "4737747"   "4888574"   "4892776"   "5336391"   "5422313"   "5422313"   "5907273"   "594997"   "6141870"   "6232042"   "6248612").PN.  [Cetch or etched or etching) with foil) and resistor  ((etch or etched or etching) with foil) and resistor  (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and resistor  (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and resistor  (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and (method or processor assembling or making or manufacturing or step) adj  persistor)  account (film or layer or coat or USPAT; US-PGPUB; IBM_TDB USPAT; US-PGPUB; USPAT;			(resistive adj (rim of rajor of	IBM TDB	
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17			etched or etching, and (rott with (chitch		
(method of process) with ror coat or cresistive adj (film or layer or coat or coating)) and substrate and ((etch or etched or etching or polishing) with foil)  17			or thickness of width;	USPAT:	2003/06/04
Cresistive add (IIIm of Taylor of Coating) and substrate and (etch or etched or etching or polishing) with foil)   17 ("2945180"   "3808576"   "3813631"   USPAT   17:03   1	_	32	((method or process) with resistor, and		
cetched or etching or polishing) with   foil)   ("2945180"   "3808576"   "3813631"   USPAT   2003/06/04   17:03   ("2945180"   "4737747"   "4888574"   "4174513"   "4737747"   "4888574"   "4892776"   "5336391"   "5422313"   "5483217"   "5756971"   "5864281"   "5907273"   "5994997"   "6141870"   "6232042"   "6248612").PN.   (29/611,10.1,620).ccls. and substrate and ((etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and (etch or etched or etching) with foil) and ((method or processor assembling or making or manufacturing or step) adj   IBM_TDB   2003/06/05   O9:18   IBM_TDB   2003/06/05   O9:18   IBM_TDB   IB			(resistive ad) (film or layer of coat of		
foil) ("2945180"   "3808576"   "3813631"   "4174513"   "4737747"   "4888574"   "4892776"   "5336391"   "5422313"   "5483217"   "5756971"   "5864281"   "5907273"   "5994997"   "6141870"   "6232042"   "6248612").PN. (29/611,10.1,620).ccls. and substrate and ((etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and ((etch or etched or etching) with foil) and ((method or processor assembling or making or manufacturing or step) adj  resistor)  1003/06/04 17:03  2003/06/05 09:15  2003/06/05 09:16  2003/06/05 09:18			coating)) and substrate and ((etch or	L PLI T L D B	
foil) ("2945180"   "3808576"   "3813631"   "4174513"   "4737747"   "4888574"   "4892776"   "5336391"   "5422313"   "5483217"   "5756971"   "5864281"   "5907273"   "5994997"   "6141870"   "6232042"   "6248612").PN. (29/611,10.1,620).ccls. and substrate and ((etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and ((method or processor assembling or making or manufacturing or step) adj  resistor)  USPAT; USPAT; USPAT; US-PGPUB; IBM_TDB			etched or etching or polishing) with		
17			foil)	WCD TO	2003/06/04
"4174513"   "4737747"   "4888574"   "4892776"   "5336391"   "5422313"   "5483217"   "5756971"   "5864281"   "5907273"   "5994997"   "6141870"   "6232042"   "6248612").PN.  14 (29/611,10.1,620).ccls. and substrate and ((etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and (method or processor assembling or making or manufacturing or step) adj  Thios  17:03  17:03  17:03  17:03  17:03  17:03	_	17	("2945180"   "3808576"   "3813631"	USPAT	
"4892776"   "5336391"   "5422313"   "5483217"   "5756971"   "5864281"   "5907273"   "5994997"   "6141870"   "6232042"   "6248612").PN.  14 (29/611,10.1,620).ccls. and substrate and ((etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and (method or processor assembling or making or manufacturing or step) adj  The sistor of the state of the s		1	"4174513"   "4737747"   "4888574"		17:03
"5483217"   "5756971"   "5864281"   "5907273"   "5994997"   "6141870"   "6232042"   "6248612").PN.  14 (29/611,10.1,620).ccls. and substrate and (etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and (etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and (etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and (etch or etched or etching) with foil) and (method or processor assembling or making or manufacturing or step) adj  The sistor of the state of the st			"4892776"   "5336391"   "5422313"		1
"5907273"   "5994997"   "6141870"   "6232042"   "6248612").PN.  14 (29/611,10.1,620).ccls. and substrate and (etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and (etch or etched or etching) with foil) and resistor (338/306-309).ccls. and substrate and (spAT; US-PGPUB; IBM_TDB us-P		1	"5483217"   "5756971"   "5864281"		
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((etch or etched of etching) with ToT7 and resistor (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and ((method or processor assembling or making or manufacturing or step) adj  TBM_TDB USPAT; US-PGPUB; IBM_TDB IBM_TDB	-	38	(338/306-309).CCIS. and substrate and		
and teststool  (338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and ((method or processor assembling or making or manufacturing or step) adj  (2003/06/05 09:18			((etch or etched or etching) with 1011)		
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and ((method or processor assembling or making or manufacturing or step) adj	-	3	(338/306-309).ccls. and substrate and		
and ((method or processor assembling or making or manufacturing or step) adj			((etch or etched or etching) with foll)		09:10
making or manufacturing or step) adj	,		and ((method or processor assembling or	TRW_LDR	
registor		1	making or manufacturing or step) adj		
70 (430/313 315 324) ccls, and substrate and USPAT; 2003/06/05			resistor)		0000/05/05
1 19 1 (430/313,343/30013, 00013, 00013, 00013, 00013, 00013, 00013, 00013, 00013, 00013, 00013, 00013, 00013,	_	79	(430/313.315.324) ccls, and substrate and	USPAT;	
((etch or etched or etching) with foil) US-PGPUB; US:19	_	1 '-	((etch or etched or etching) with foil)	US-PGPUB;	09:19
IBM TDB	1		1100011 02 0001111	IBM_TDB	

<del>-</del> .	13	(430/313,315,324).ccls. and substrate and	USPAT;	2003/06/05
<b>-</b> .	13	((etch or etched or etching) with foil)	US-PGPUB;	09:19
1	ļ			03.23
	1	and resistor	IBM_TDB	
	1 1	(438/462,977).ccls. and substrate and	USPAT;	2003/06/05
] -	1 1	(etch or etched or etching) and foil and	US-PGPUB;	09:20
	1		IBM TDB	
		resistor		2022/26/05
1_	18	3669022.URPN.	USPAT	2003/06/05
_	1 10	500502210112111		10:42
			USPAT	2003/06/05
Ì -	1	6232042.URPN.	USPAI	- · · · · · · · · · · · · · · · · · · ·
	1			10:46
-	1	6194990.pn.	USPAT;	2003/06/05
-	1 1	6194990.pm.	US-PGPUB;	11:20
	i			12.20
			IBM_TDB	2222125125
	11	("3719508"   "4786564"   "4888574"	USPAT	2003/06/05
ļ <del>-</del>	++	"4892776"   "5053318"   "5336391"		10:48
		489Z//6   3033310   3330331		1
		"5347258"   "5403672"   "5560812"		
		"5679498"   "6171921").PN.		
	11	4297670.URPN.	USPAT	2003/06/05
<b>-</b> '	11	429/0/0.URFN.		10:50
}				
1_	12	("2945180"   "3808576"   "3813631"	USPAT	2003/06/05
		"4174513"   "4888574"   "4892776"		10:51
		71/7010   70000/1   1000/17#		]
		"5336391"   "5422313"   "5483217"	ì	
	_ [	"5756971"   "5864281"   "5907273").PN.	l	0000105105
	3	6194990.URPN.	USPAT	2003/06/05
1 -	ادا	V_J + J J V   V+   M +   1		10:52
1			USPAT;	2003/06/05
-	11	laminated adj resistor		1 ·
		,	US-PGPUB;	11:21
1		1	IBM TDB	
			USPAT;	2003/06/05
l –	1988	chip adj resistor		1 = 1 1
	İ		US-PGPUB;	11:30
			IBM TDB	
,			USPAT;	2003/06/05
<b> </b> -	570	(chip adj resistor) and glass		11:22
			US-PGPUB;	11:22
			IBM TDB	
		(chip adj resistor) and glass and	USPAT;	2003/06/05
-	328		US-PGPUB;	11:22
		terminal		11.22
			IBM_TDB	1
1	100	(chip adj resistor) and glass and	USPAT;	2003/06/05
<del>-</del>	126	(Chip ad) resistory and grass and	US-PGPUB;	11:23
		terminal and nickel	1	11.23
i			IBM_TDB	
	126	(method or process or manufacturing or	USPAT;	2003/06/05
-	126	(method of process of managed and (chin	US-PGPUB;	11:24
		making or producing or steps) and (chip		1
1		adj resistor) and glass and terminal and	IBM_TDB	1
		nickel		
			USPAT;	2003/06/05
-	11	(method of process of manufacturing of	US-PGPUB;	11:24
		making or producing or steps) adj (chip		1
		adj resistor) and glass and terminal and	IBM_TDB	
		nickel	_	
1			USPAT	2003/06/05
-	5	("3167451"   "4437140"   "4684916"	1	11:28
		"5510594"   "5680092").PN.		
1_	30	(29/610.1,620,621).ccls. and (chip adj	USPAT;	2003/06/05
-	1	resistor)	US-PGPUB;	11:39
		TESTSCOTI	IBM TDB	
1			USPAT	2003/06/05
-	10	4267634.URPN.	OSPAT	
1				11:36
1	-	(29/610.1,620,621).ccls. and (chip adj	USPAT;	2003/06/05
-	5	(25/010.1,020,021/.0015. and (0111p da)	US-PGPUB;	11:40
	1	resistor) and multilayer		
			IBM_TDB	2000/25/25
1	11	(338/308,309,332).ccls. and (chip adj	USPAT;	2003/06/05
-	11	(JJO) JOO JOO JOO JOO JOO COLLEGE COLL	US-PGPUB;	11:41
		resistor) and multilayer	IBM TDB	_
				2002/06/05
_	. 13	5170146.URPN.	USPAT	2003/06/05
-	. 13			11:42
		FOOTIOGS VIDEN	USPAT	2003/06/05
-	10	5287083.URPN.	051711	11:47
1_	1	4267634.pn. and glass	USPAT;	2003/06/05
-	1	120,001,5	US-PGPUB;	13:32
			IBM TDB	1
				2002/06/06
_	10	4267634.URPN.	USPAT	2003/06/05
1			1	13:12
1	ı			

			HCDATT.	2003/06/05
	0	multilayered adj resistor	USPAT; US-PGPUB;	13:16
	1		IBM TDB	
			USPAT;	2003/06/05
_	8	multi-layered near resistor	US-PGPUB;	13:20
	1		IBM TDB	
			USPAT;	2003/06/05
-	32723	ceramic near glass	US-PGPUB;	13:20
ĺ	1		IBM TDB	
	24.0	(ceramic near glass) and resistor	USPAT;	2003/06/05
-	3649	(ceramic near glass) and lesistor	US-PGPUB;	13:21
			IBM TDB	
	0.1	(ceramic near glass) and (chip adj	USPAT;	2003/06/05
-	81	resistor)	US-PGPUB;	13:21
		lesiscor	IBM TDB	
	0	4267634.pn. and nickel	USPĀT;	2003/06/05
-	"	4207054.pii. ana iizonoz	US-PGPUB;	13:36
			IBM_TDB	
	3612	nickel with melting	USPAT;	2003/06/05
-	3612	HIGHOI WIGHT WITTEN	US-PGPUB;	13:37
1			IBM_TDB	
1	2226	nickel with (melting adj (point or	USPAT;	2003/06/05
1 -	2226	temperature))	US-PGPUB;	13:38
			IBM_TDB	2000/05/05
	314	nickel near (melting adj (point or	USPAT;	2003/06/05
-	314	temperature))	US-PGPUB;	13:39
			IBM_TDB	/
	17	nickel near (melting adj (point or	USPAT;	2003/06/05
-	1 1/	temperature)) and resistor	US-PGPUB;	13:50
1		temperature// und rober-	IBM_TDB	
	9	palladium near (melting adj (point or	USPAT;	2003/06/05
-	9	temperature)) and resistor	US-PGPUB;	13:51
		temperature// and restroy	IBM TDB	
	0	(29/619).ccls. and (chip adj resistor)	USPAT;	2003/06/05
-	1	and multilayer	US-PGPUB;	15:03
		and murchayer	IBM_TDB	
	1 7	(29/611,610.1,619,620,621).ccls. and	USPAT;	2003/06/05
-	17	substrate and ((etch or etched or	US-PGPUB;	15:05
		etching) with foil) and resistor	IBM_TDB	
	15		USPĀT;	2003/06/05
-	15	substrate and ((etch or etched or	US-PGPUB;	15:08
		etching) with foil) and resistor	IBM_TDB	
1	21	(174/260) ccls and substrate and ((etcn	USPAT;	2003/06/05
-	31	or etched or etching) with foil) and	US-PGPUB;	15:08
		registor	IBM_TDB	
	10	(174/260) ccls, and substrate and ((etch	USPAT;	2003/06/05
-	1 19	or etched or etching) with foil) and	US-PGPUB;	15:09
1		istor and multilaver\$3	IBM_TDB	
	2		USPAT;	2003/11/12
-	2	adj resistor	OS-FGEOD!	17:20
,		auj resiscor	IBM_TDB	
	15	"5488348"	USPAT;	2004/05/18
-	15	7400740	US-PGPUB;	18:05
1			IBM_TDB	
	-	5488348.pn.	USPAT;	2004/05/18
-	1	. 1400240.bit.	US-PGPUB;	18:11
			IBM_TDB	
	١ ,	(95/31816).CCLS.	EPO	2004/05/18
-		(33/31010).0000.		18:12
		(WO95/31816).CCLS.	EPO	2004/05/18
-	1	) (WO33/31010/.0010.		18:12
		("WO9531816").PN.	EPO	2004/05/18
-		)   ("WO9531816").PN.		18:12
-		(("5303115") or ("3775725") or	EPO	2004/05/19
-	(	) (("5303115") or ("3//5/25") or		13:55
		("4924074")).PN. 6 (("5303115") or ("3775725") or	USPAT;	2004/05/19
-	1	6 (("5303115") or ("3//5/25") or	US-PGPUB;	1
		("4924074")).PN.	DERWENT;	
			IBM TDB	
1	i			

_	3	(("5303115") or ("3775725") or	USPAT;	2004/05/19
	-	("4924074")).PN.	US-PGPUB;	13:55
		( 1001010 ) , , 1 1 1 1 1	IBM TDB	1
	1 1	("6606023").PN.	USPAT;	2004/05/19
-	1 1	(~6606023 ).PN.	US-PGPUB;	14:32
				13.32
			IBM_TDB	0004/05/10
_	0	("6311390").PN.	EPO	2004/05/19
				15:27
_	1	("6311390").PN.	USPAT;	2004/05/19
-	<u> </u>	( 0311330 /.1	US-PGPUB;	17:16
İ			IBM TDB	
			USPAT	2004/05/19
-	5	("5488348"   "5493266"   "6020808"	USPAI	
1		"6040755"   "6157289").PN.		15:29
	5	(thermistor adj strip) and glass	USPAT;	2004/05/19
		, , , , , , , , , , , , , , , , , , , ,	US-PGPUB;	15:37
İ	}		IBM TDB	ĺ
	4.0	(1) and along	USPAT;	2004/05/19
-	48	(thermistor adj chip) and glass	US-PGPUB;	15:40
				13.40
İ			IBM_TDB	
_	13	(thermistor adj chip) and glass and	USPAT;	2004/05/19
1		alumina	US-PGPUB;	15:40
		Committee	IBM TDB	
		(thermistor adj chip) and glass and	USPAT;	2004/05/19
-	1	(thermistor adj chip) and grass and	US-PGPUB;	16:12
		alumina and ruthenium		1 -0.12
			IBM_TDB	0004 (05 (30
_	55	((thermistor adj chip) or (chip adj	USPAT;	2004/05/19
		resistor)) and glass and alumina and	US-PGPUB;	16:29
		ruthenium	IBM TDB	
	10	1	USPAT;	2004/05/19
-	12	((thermistor adj chip) or (chip adj	US-PGPUB;	16:33
		resistor)) and glass and alumina and		10.55
1		ruthenium and stack\$3	IBM_TDB	0004/05/10
<u>-</u>	6	((thermistor adj chip) or (chip adj	USPAT;	2004/05/19
1	_	resistor)) and glass and (alumina adj	US-PGPUB;	16:34
•		substrate) and ruthenium and stack\$3	IBM TDB	
	1	• • •	USPAT;	2004/05/19
-	1	6311390.pm. and grass	US-PGPUB;	17:16
	i		1	17.10
			IBM_TDB	2004/05/10
l <b>-</b>	0	6311390.pn. and glass and alumina	USPAT;	2004/05/19
			US-PGPUB;	17:16
1	1		IBM TDB	
	1 0	6311390.pn. and glass and ruthenium	USPAT;	2004/05/19
.   -	"	6511590.pii. and grass and ruenenzam	US-PGPUB;	17:17
			IBM TDB	1 - / • - /
				2004/05/10
_	1	"3353124".PN.	USPAT	2004/05/19
				17:52
	1	("6362723").PN.	USPAT;	2004/05/19
-	1	1 0002/20 /	US-PGPUB;	18:07
			IBM TDB	
		land the second	USPAT;	2004/05/19
-	6	((thermistor near chip) or (chip near		18:13
		resistor)) and glass and (alumina adj	US-PGPUB;	10.13
		substrate) and ruthenium and stack\$3	IBM_TDB	
_	914	((thermistor near chip) or (chip near	USPAT;	2004/05/19
		resistor)) and glass	US-PGPUB;	18:20
		Topincol/, ama grand	IBM TDB	
	1	(1)	USPAT;	2004/05/19
-	121	((thermistor near chip) or (chip near	US-PGPUB;	18:12
1 .		resistor)) and glass and (alumina adj		10.12
1		substrate)	IBM_TDB	0004/05/20
_	33	((thermistor near chip) or (chip near	USPAT;	2004/05/19
1		resistor)) and glass and (alumina adj	US-PGPUB;	18:25
1	1	substrate) and ruthenium	IBM TDB	1
			USPAT;	2004/05/19
-	77	((thermistor hear chip) or (chip hear	US-PGPUB;	18:21
	1	resistor)) and (glass adj substrate)	1 '	10.21
			IBM_TDB	0004/05/10
_	20	((thermistor near chip) or (chip near	USPAT;	2004/05/19
		resistor)) and glass and (alumina adj	US-PGPUB;	18:25
		substrate) and ruthenium and plat\$3	IBM TDB	
	_		USPAT;	2004/05/19
-	6	((thermistor hear chip) or (chip hear	US-PGPUB;	18:26
		resistor)) and glass and (alumina adj		10.20
		substrate) and ruthenium and (nickel near	IBM_TDB	
		plat\$3)		
L				•

-	0	6124769.pn and alumina and ruthenium	USPAT; US-PGPUB;	2004/05/20
-	1	"3353124".PN.	IBM_TDB USPAT	2004/05/20
_	6	(29/612).ccls. and ((thermistor near chip) or (chip near resistor)) and glass	USPAT; US-PGPUB; IBM TDB	2004/05/20
-	1	(333/172).ccls. and ((thermistor near chip) or (chip near resistor)) and (alumina adj substrate) and ruthenium and	USPAT; US-PGPUB; IBM_TDB	2004/05/20 15:29
		stack\$3		